



Material Content Data Sheet



Sales Product Name	BTS6163D			Issued	19. January 2018			
MA#	MA000267882							
Package	PG-TO252-5-11			Weight*	357.37 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.583	1.56	1.56	15622	15622
leadframe	non noble metal	iron	7439-89-6	0.205	0.06		572	
	inorganic material	phosphorus	7723-14-0	0.061	0.02		172	
	non noble metal	copper	7440-50-8	204.243	57.15	57.23	571514	572258
wire	non noble metal	aluminium	7429-90-5	1.978	0.55	0.55	5535	5535
encapsulation	organic material	carbon black	1333-86-4	1.366	0.38		3822	
	plastics	epoxy resin	-	23.902	6.69		66883	
	inorganic material	silicondioxide	60676-86-0	111.316	31.15	38.22	311485	382190
leadfinish	non noble metal	tin	7440-31-5	5.072	1.42	1.42	14194	14194
plating	non noble metal	nickel	7440-02-0	0.076	0.02		213	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	214
glue	plastics	Polyimide	26023-21-2	0.143	0.04	0.04	399	399
solder	noble metal	silver	7440-22-4	0.086	0.02		240	
	non noble metal	tin	7440-31-5	0.069	0.02		192	
	non noble metal	lead	7439-92-1	3.272	0.92	0.96	9156	9588
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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